

Appl. No. 10/510,588; Docket No. NL02 1100US  
Amdt. dated September 8, 2006  
Response to Office Action dated August 25, 2006

**Amendments to the Claims**

**Claims 1-3 (*Cancelled*)**

4. (*Original*) A carrier with a first and a second side, comprising a stack of:

- a first etch mask,
- a first metal layer,
- an intermediate layer,
- a second metal layer and
- a second etch mask,

the first etch mask being situated on the first side of the carrier, and the second etch mask being situated on the second side of the carrier.

5. (*Original*) A carrier as claimed in claim 4, characterized in that the first metal layer and the intermediate layer are patterned such that the first metal layer comprises parts projecting with respect to the intermediate layer.

6. (*Previously Presented*) A carrier as claimed in claim 4, characterized in that the first and the second etch mask comprise an adhesive layer for solder.

7. (*Original*) A carrier as claimed in claim 6, characterized in that the adhesive layer for solder comprises a material selected from the group composed of Ag, NiPd, NiPdAu.

8. (*Previously Presented*) A carrier as claimed in claim 4, characterized in that the intermediate layer comprises an electroconductive material that can suitably be used as a solder stop.

9. (*Original*) A carrier as claimed in claim 8, characterized in that the intermediate layer comprises a material selected from the group composed of Al, an alloy of Al, FeNi, FeCrNi and stainless steel, and that the first and the third metal layer contain copper.

**Claims 10-12 (*Cancelled*)**